

IN THE SPECIFICATION

Please rewrite the paragraph on page 5, lines 9-11, as follows:

Fig. 1 is a vertical sectional view showing a single circuit board in accordance with a first embodiment of the present invention.

Please rewrite the paragraphs beginning on page 5, line 21, and ending on page 6, line 3, as follows:

Fig. 6 is a top plan view showing a single circuit board in accordance with a second embodiment after an interconnect layer and a floating conductive layer are formed.

Fig. 7 is a top plan view showing a single circuit board in accordance with a third embodiment after an interconnect layer and a floating conductive layer are formed.